## PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

## **CONVEYING PARTY DATA**

Name	Execution Date
Haruhisa SAITO	04/01/2013
Yoshitaka TADAKI	04/01/2013

#### **RECEIVING PARTY DATA**

Name:	OLYMPUS CORPORATION	
Street Address:	43-2, Hatagaya 2-chome, Shibuya-ku	
City:	Tokyo	
State/Country:	JAPAN	

## PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	13845597

#### **CORRESPONDENCE DATA**

Fax Number: 2028221111

Correspondence will be sent via US Mail when the fax attempt is unsuccessful.

Email: patentmail@whda.com

Correspondent Name: Westerman, Hattori, Daniels & Adrian, LL

Address Line 1: 1250 Connecticut Ave, NW

Suite 700 Address Line 2:

Address Line 4: Washington, DISTRICT OF COLUMBIA 20036

ATTORNEY DOCKET NUMBER:	130360
NAME OF SUBMITTER:	Tsuyoshi Nakamura
Signature:	/Tsuyoshi NAKAMURA/
Date:	04/18/2013

Total Attachments: 1

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**PATENT** REEL: 030244 FRAME: 0878

Docket	Nο	
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Westerman, Hattori, Daniels & Adrian, LLP

## U.S. ASSIGNMENT

IN CONSIDERATION of the sum of One Dollar (\$1.00), and of other good and valuable consideration paid to the undersigned inventor(s) (hereinafter ASSIGNOR) by

(Insert ASSIGNEE's Name(s) Address(es))

**OLYMPUS CORPORATION** 

of 43-2, Hatagaya 2-chome, Shibuya-ku, Tokyo, Japan

(hereinafter ASSIGNEE), the receipt of which is hereby acknowledged, the undersigned ASSIGNOR hereby sells, assigns and transfers to ASSIGNEE the entire and exclusive right, title and interest to the invention entitled

(Title of Invention)

SEMICONDUCTOR WAFER AND SEMICONDUCTOR DEVICE

(\*If the assignment is being filed after the filing of the application, this section must be completed) for which application for Letters Patent of the United States was executed on even date herewith unless otherwise indicated below:

\* filed on \_\_\_\_\_ Serial No. 13/845,597

(Westerman, Hattori, Daniels & Adrian, LLP is hereby authorized to insert the series code, serial number and/or filing date hereon, when known)

and all Letters Patent of the United States to be obtained therefore on said application or any continuation, divisional, substitute, reissue or reexamination thereof for the full term or terms for which the same may be granted.

The ASSIGNOR agrees to execute all papers necessary in connection with the application and any continuation, divisional, reissue or reexamination applications thereof and also to execute separate assignments in connection with such applications as the ASSIGNEE may deem necessary or expedient.

The ASSIGNOR agrees to execute all papers necessary in connection with any interference, litigation, or other legal proceeding which may be declared concerning this application or any continuation, divisional, reissue or reexamination thereof or Letters Patent or reissue patent issued thereon and to cooperate with the ASSIGNEE in every way possible in obtaining and producing evidence and proceeding with such interference, litigation, or other legal proceeding.

IN WITNESS WHEREOF, the undersigned inventor(s) has (have) affixed his/her/their signature(s).

(Signatures)

Harrhisa Saite	Haruhisa SAITO	Apr. 1,2013
(Signature)	(Type Name)	(Date)
Yoshtaken Tadaki (Signature)	Yoshitaka TADAKI	Apr. 1. 2013
(Signature)	(Type Name)	(Date)

NO LEGALIZATION REQUIRED

PATENT REEL: 030244 FRAME: 0879

**RECORDED: 04/18/2013**